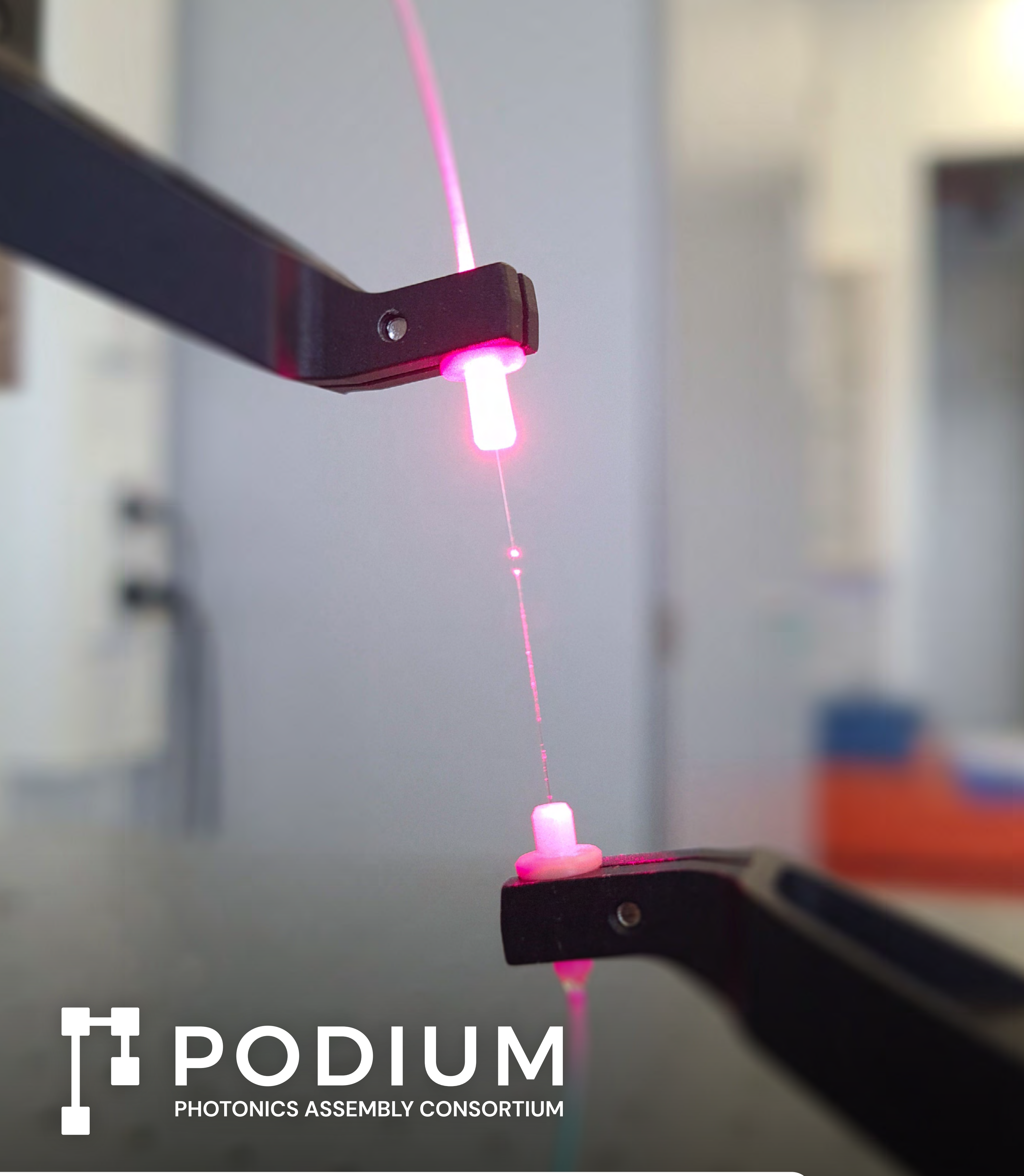
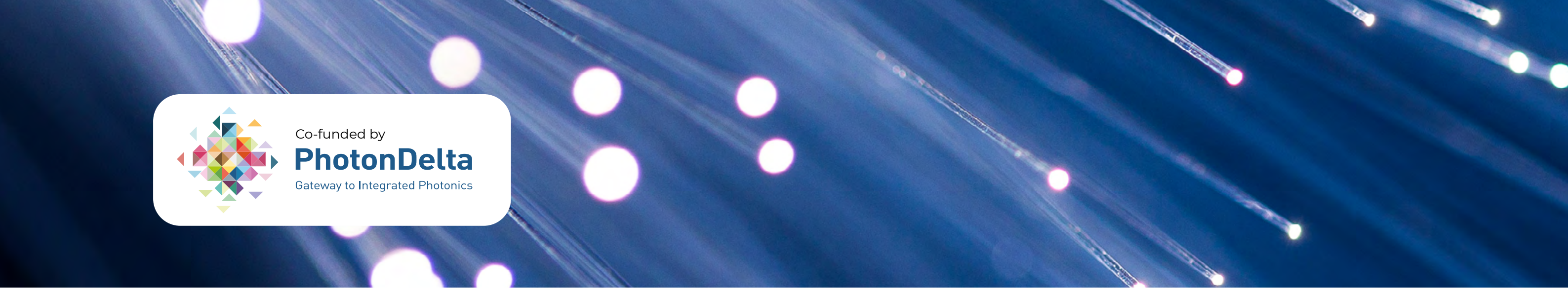


PODIUM

PHOTONICS ASSEMBLY CONSORTIUM

PODIUM: a unique ecosystem to accelerate and standardize the packaging of integrated photonics

CITC Chip Integration Technology Center
finetech
phix
PI
TEGEMA An Etteplan company



Co-funded by
PhotonDelta
Gateway to Integrated Photonics

Speeding up development and production

PODIUM *(PICs Open Development Infrastructure for Universal Markets)* is a unique photonics assembly consortium that combines the electrical and optical packaging know-how of its partners to accelerate assembly process development and provide an efficient path to volume OSAT or captive fabrication. We provide direct access to flexible, high-throughput automation tooling that enables you to develop photonic assembly processes including the industrialization steps. We enable you to efficiently and reliably produce the devices and systems your customers are asking for in an optimal timeframe.

Knowledge, expertise and capabilities of five partners

PODIUM is unique as it offers a combination of access to research institutes, experienced photonics companies and equipment technology.

By combining the knowledge, expertise and current solutions of CITC (process development), TEGEMA (active fiber alignment equipment), Finetech (die bonding equipment), PI (key module supplier) and PHIX (PICS packaging foundry), we approach your challenge from all sides. This approach gives maximum flexibility and secures both the quality of the solution and the means to mass produce the process solutions that are developed with sufficient quality and volumes. PODIUM thus provides a ‘one-stop shop’ from process development to mass production.

Optimizing your packaging solution

With lab facilities of CITC, new processes will be developed and optimized for and with you. CITC utilizes Finetech tools and the TEGEMA modular equipment platform for active fiber alignment, which allows integration of a wide range of motion, process and handling modules. The platform uses state-of-the art motion hardware and firmware of PI, which enables ultra-high motion precision and active optical alignment routines. PODIUM will help you to optimize your packaging solution before bringing it to volume production, either by transferring the outcome to PHIX, offering high-volume optical assembly services, or in-house production.

PODIUM OFFERS YOU:

- Access to a low-entry and low cost of ownership platform for captive production
- The ability to develop your photonic assembly processes including volume scaling by a foundry packaging and assembly partner
- A ‘one-stop shop’ from development to volume production

More about the PODIUM partners

PODIUM runs a program in which optical termination technology, assembly and packaging is developed for a wide range of integrated photonic applications. You can rely on the abilities of PODIUM's five partners because, as Aristotle said 2,000 years ago, the whole is greater than the sum of its parts. Get to know the partners in more detail:

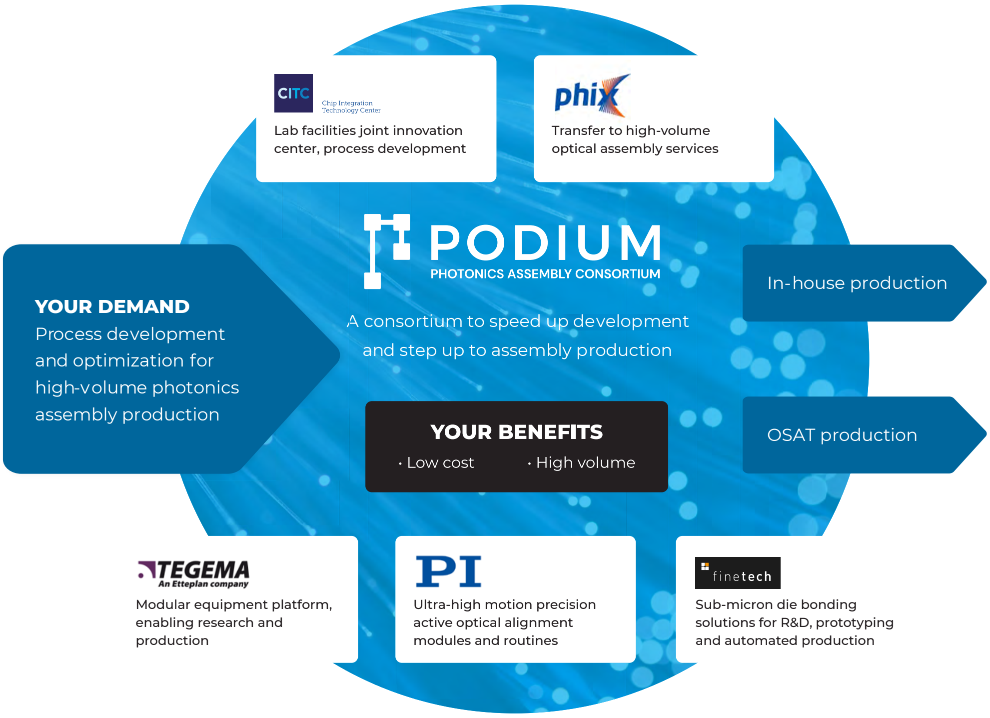
Joint innovation center **CITC – Chip Integration Technology Center** is specialized in heterogeneous integration and advanced chip packaging technology - **www.citc.org**

Finetech is the leading equipment manufacturer for sub-micron die and flip-chip bonding with a strong customer base in the photonics markets - **www.finetech.de**

PHIX is a fully independent foundry for packaging and assembly of Photonic Integrated Circuits in scalable production volumes, supporting all major technology platforms - **www.phix.com**

PI (Physik Instrumente) is the market and technology leader for high-precision positioning technology and piezo applications in the semiconductor industry and photonics - **www.physikinstrumente.com**

TEGEMA is a multidisciplinary system integrator who combines its experience in customized precision mechanics and mechatronics with the latest robotics, software and big data technologies to optimize production performance - **www.tegema.nl**



Lab facilities joint innovation center, process development

Transfer to high-volume optical assembly services

PODIUM
PHOTONICS ASSEMBLY CONSORTIUM

A consortium to speed up development and step up to assembly production

YOUR DEMAND
Process development and optimization for high-volume photonics assembly production

In-house production

OSAT production

YOUR BENEFITS
· Low cost · High volume

Modular equipment platform, enabling research and production

Ultra-high motion precision active optical alignment modules and routines

Sub-micron die bonding solutions for R&D, prototyping and automated production

Contact us

Would you like to find out how PODIUM can speed up the development and production of your packaging solution? Please visit **www.podiumpackaging.com** or contact Marco Koelink, Business Development Manager at **+31 6 15 15 66 41**

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